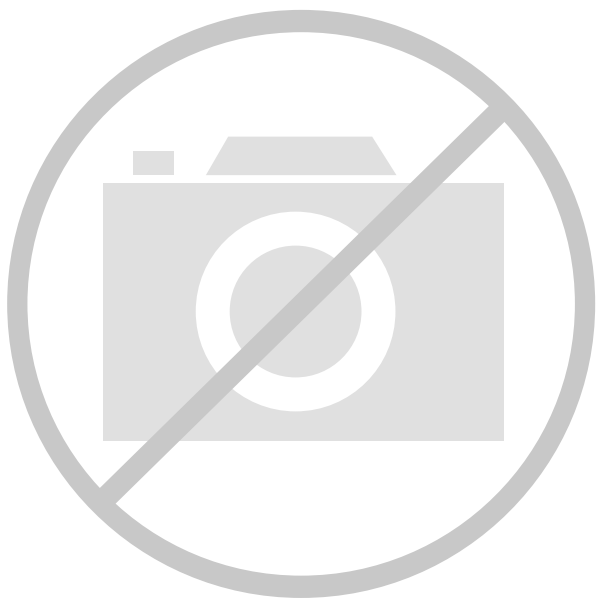




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	9600
Number of Logic Elements/Cells	43200
Total RAM Bits	655360
Number of I/O	512
Number of Gates	2541952
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	680-LBGA Exposed Pad
Supplier Device Package	680-FTEBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv2000e-6fg680c

Table 1: Virtex-E Field-Programmable Gate Array Family Members

Device	System Gates	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	BlockRAM Bits	Distributed RAM Bits
XCV50E	71,693	20,736	16 x 24	1,728	83	176	65,536	24,576
XCV100E	128,236	32,400	20 x 30	2,700	83	196	81,920	38,400
XCV200E	306,393	63,504	28 x 42	5,292	119	284	114,688	75,264
XCV300E	411,955	82,944	32 x 48	6,912	137	316	131,072	98,304
XCV400E	569,952	129,600	40 x 60	10,800	183	404	163,840	153,600
XCV600E	985,882	186,624	48 x 72	15,552	247	512	294,912	221,184
XCV1000E	1,569,178	331,776	64 x 96	27,648	281	660	393,216	393,216
XCV1600E	2,188,742	419,904	72 x 108	34,992	344	724	589,824	497,664
XCV2000E	2,541,952	518,400	80 x 120	43,200	344	804	655,360	614,400
XCV2600E	3,263,755	685,584	92 x 138	57,132	344	804	753,664	812,544
XCV3200E	4,074,387	876,096	104 x 156	73,008	344	804	851,968	1,038,336

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectI/O technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250 MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT} , the supply voltage for the internal logic and memory, is 1.8 V, instead of 2.5 V for Virtex devices. Advanced processing and 0.18 μ m design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3 V tolerant, and can be 5 V tolerant with an external 100 Ω resistor. PCI 5 V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT} . With Virtex-E devices, the LVTTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO} .

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 μ m CMOS process. These advances make Virtex-E FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The Virtex-E family includes the nine members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. Table 19 summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Table 19: Xilinx Input Standards Compatibility Requirements

Rule 1	Standards with the same input V_{CCO} , output V_{CCO} , and V_{REF} can be placed within the same bank.
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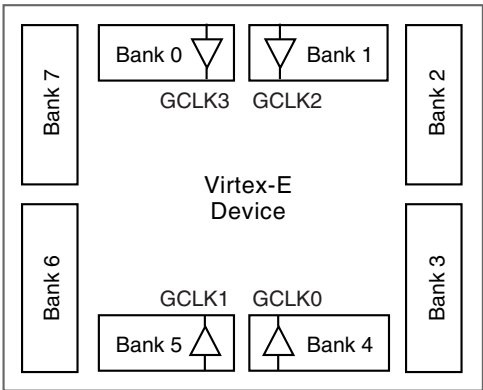


Figure 38: Virtex-E I/O Banks

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG should only drive a CLKDLL,

CLKDLLHF, or BUFG symbol. The generic Virtex-E IBUFG symbol appears in Figure 39.

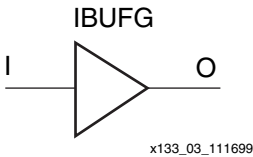


Figure 39: Virtex-E Global Clock Input Buffer (IBUFG) Symbol

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF} .

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

As an added convenience, the BUFGP can be used to instantiate a high fanout clock input. The BUFGP symbol

represents a combination of the LVTTTL IBUFG and BUFG symbols, such that the output of the BUFGP can connect directly to the clock pins throughout the design.

Unlike previous architectures, the Virtex-E BUFGP symbol can only be placed in a global clock pad location. The LOC property can specify a location for the BUFGP.

OBUF

An OBUF must drive outputs through an external output port. The generic output buffer (OBUF) symbol appears in Figure 40.

The extension to the base name defines which I/O standard the OBUF uses. With no extension specified for the generic OBUF symbol, the assumed standard is slew rate limited LVTTTL with 12 mA drive strength.

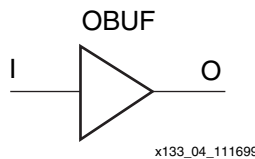


Figure 40: Virtex-E Output Buffer (OBUF) Symbol

The LVTTTL OBUF additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

LVTTTL output buffers have selectable drive strengths.

The format for LVTTTL OBUF symbol names is as follows:

OBUF_<slew_rate>_<drive_strength>

where <slew_rate> is either F (Fast) or S (Slow), and <drive_strength> is specified in milliamps (2, 4, 6, 8, 12, 16, or 24).

The following list details variations of the OBUF symbol.

- OBUF
- OBUF_S_2
- OBUF_S_4
- OBUF_S_6
- OBUF_S_8
- OBUF_S_12
- OBUF_S_16
- OBUF_S_24
- OBUF_F_2
- OBUF_F_4
- OBUF_F_6
- OBUF_F_8
- OBUF_F_12
- OBUF_F_16
- OBUF_F_24
- OBUF_LVCMOS2
- OBUF_PCI33_3

- OBUF_PCI66_3
- OBUF_GTL
- OBUF_GTLP
- OBUF_HSTL_I
- OBUF_HSTL_III
- OBUF_HSTL_IV
- OBUF_SSTL3_I
- OBUF_SSTL3_II
- OBUF_SSTL2_I
- OBUF_SSTL2_II
- OBUF_CTT
- OBUF_AGP
- OBUF_LVCMOS18
- OBUF_LVDS
- OBUF_LVPECL

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS packages support four V_{CCO} banks.

OBUF placement restrictions require that within a given V_{CCO} bank each OBUF share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within any V_{CCO} bank. Table 20 summarizes the Virtex-E output compatibility requirements. The LOC property can specify a location for the OBUF.

Table 20: Output Standards Compatibility Requirements

Rule 1	Only outputs with standards that share compatible V_{CCO} can be used within the same bank.
Rule 2	There are no placement restrictions for outputs with standards that do not require a V_{CCO} .
V_{CCO}	Compatible Standards
3.3	LVTTTL, SSTL3_I, SSTL3_II, CTT, AGP, GTL, GTL+, PCI33_3, PCI66_3
2.5	SSTL2_I, SSTL2_II, LVCMOS2, GTL, GTL+
1.5	HSTL_I, HSTL_III, HSTL_IV, GTL, GTL+

OBUFT

The generic 3-state output buffer OBUFT (see Figure 41) typically implements 3-state outputs or bidirectional I/O.

The extension to the base name defines which I/O standard OBUFT uses. With no extension specified for the generic OBUFT symbol, the assumed standard is slew rate limited LVTTTL with 12 mA drive strength.

The LVTTTL OBUFT additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

Table 42: Input Library Macros

Name	Inputs	Outputs
IBUFDS_FD_LVDS	I, IB, C	Q
IBUFDS_FDE_LVDS	I, IB, CE, C	Q
IBUFDS_FDC_LVDS	I, IB, C, CLR	Q
IBUFDS_FDCE_LVDS	I, IB, CE, C, CLR	Q
IBUFDS_FDP_LVDS	I, IB, C, PRE	Q
IBUFDS_FDPE_LVDS	I, IB, CE, C, PRE	Q
IBUFDS_FDR_LVDS	I, IB, C, R	Q
IBUFDS_FDRE_LVDS	I, IB, CE, C, R	Q
IBUFDS_FDS_LVDS	I, IB, C, S	Q
IBUFDS_FDSE_LVDS	I, IB, CE, C, S	Q
IBUFDS_LD_LVDS	I, IB, G	Q
IBUFDS_LDE_LVDS	I, IB, GE, G	Q
IBUFDS_LDC_LVDS	I, IB, G, CLR	Q
IBUFDS_LDCE_LVDS	I, IB, GE, G, CLR	Q
IBUFDS_LDP_LVDS	I, IB, G, PRE	Q
IBUFDS_LDPE_LVDS	I, IB, GE, G, PRE	Q

Creating LVDS Output Buffers

LVDS output buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both output buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one HIGH and one LOW). Failure to follow these rules leads to DRC errors in software.

VHDL Instantiation

```
data0_p : OBUF_LVDS port map
(I=>data_int(0), O=>data_p(0));

data0_inv: INV      port map
(I=>data_int(0), O=>data_n_int(0));

data0_n : OBUF_LVDS port map
(I=>data_n_int(0), O=>data_n(0));
```

Verilog Instantiation

```
OBUF_LVDS data0_p (.I(data_int[0]),
.O(data_p[0]));

INV      data0_inv (.I(data_int[0],
.O(data_n_int[0]));

OBUF_LVDS data0_n (.I(data_n_int[0]),
.O(data_n[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P
NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous Outputs

If the outputs are synchronous (registered in the IOB) then any IO_L#PIN pair can be used. If the outputs are asynchronous (no output register), then they must use one of the pairs that are part of the same IOB group at the end of a ROW or COLUMN in the device.

The LVDS pairs that can be used as asynchronous outputs are listed in the Virtex-E pinout tables. Some pairs are marked as asynchronous-capable for all devices in that package, and others are marked as available only for that device in the package. If the device size might change at some point in the product lifetime, then only the common pairs for all packages should be used.

Adding an Output Register

All LVDS buffers can have an output register in the IOB. The output registers must be in both the P-side and N-side IOBs. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The clock pin (C), clock enable (CE) and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map-pr [ilolb]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The output library macros are listed in Table 43. The O and OB inputs to the macros are the external net connections.

Virtex-E Electrical Characteristics

Definition of Terms

Electrical and switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Each designation is defined as follows:

Advance: These speed files are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These speed files are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production: These speed files are released once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

All specifications are representative of worst-case supply voltage and junction temperature conditions. The parameters included are common to popular designs and typical applications. Contact the factory for design considerations requiring more detailed information.

Table 1 correlates the current status of each Virtex-E device with a corresponding speed file designation.

Table 1: Virtex-E Device Speed Grade Designations

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XCV50E			-8, -7, -6
XCV100E			-8, -7, -6
XCV200E			-8, -7, -6
XCV300E			-8, -7, -6
XCV400E			-8, -7, -6
XCV600E			-8, -7, -6
XCV1000E			-8, -7, -6
XCV1600E			-8, -7, -6
XCV2000E			-8, -7, -6
XCV2600E			-8, -7, -6
XCV3200E			-8, -7, -6

All specifications are subject to change without notice.

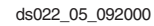


Figure 2: Detailed View of Virtex-E Slice

CLB Distributed RAM Switching Characteristics

		Speed Grade ⁽¹⁾				Units
Description	Symbol	Min	-8	-7	-6	
Sequential Delays						
Clock CLK to X/Y outputs (WE active) 16 x 1 mode	T _{SHCKO16}	0.67	1.38	1.5	1.7	ns, max
Clock CLK to X/Y outputs (WE active) 32 x 1 mode	T _{SHCKO32}	0.84	1.66	1.9	2.1	ns, max
Shift-Register Mode						
Clock CLK to X/Y outputs	T _{REG}	1.25	2.39	2.9	3.2	ns, max
Setup and Hold Times before/after Clock CLK						
F/G address inputs	T _{AS} /T _{AH}	0.19 / 0	0.38 / 0	0.42 / 0	0.47 / 0	ns, min
BX/BY data inputs (DIN)	T _{DS} /T _{DH}	0.44 / 0	0.87 / 0	0.97 / 0	1.09 / 0	ns, min
SR input (WE)	T _{WS} /T _{WH}	0.29 / 0	0.57 / 0	0.7 / 0	0.8 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{WPH}	0.96	1.9	2.1	2.4	ns, min
Minimum Pulse Width, Low	T _{WPL}	0.96	1.9	2.1	2.4	ns, min
Minimum clock period to meet address write cycle time	T _{WC}	1.92	3.8	4.2	4.8	ns, min
Shift-Register Mode						
Minimum Pulse Width, High	T _{SRPH}	1.0	1.9	2.1	2.4	ns, min
Minimum Pulse Width, Low	T _{SRPL}	1.0	1.9	2.1	2.4	ns, min

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

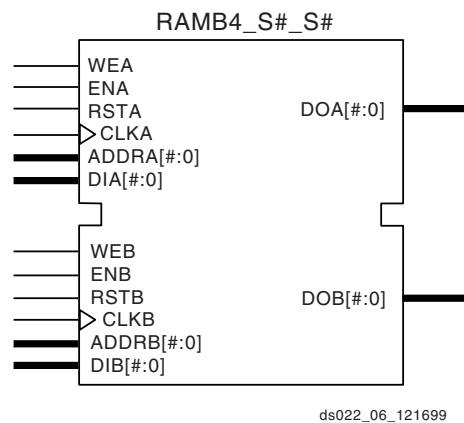


Figure 3: Dual-Port Block SelectRAM

Global Clock Set-Up and Hold for LVTTL Standard, *without* DLL

Description ⁽¹⁾	Symbol	Device	Speed Grade ^(2, 3)				Units
			Min	-8	-7	-6	
Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in IOB Input Switching Characteristics Standard Adjustments , page 8.							
Full Delay Global Clock and IFF, without DLL	T _{PSFD} /T _{PHFD}	XCV50E	1.8 / 0	1.8 / 0	1.8 / 0	1.8 / 0	ns
		XCV100E	1.8 / 0	1.8 / 0	1.8 / 0	1.8 / 0	ns
		XCV200E	1.9 / 0	1.9 / 0	1.9 / 0	1.9 / 0	ns
		XCV300E	2.0 / 0	2.0 / 0	2.0 / 0	2.0 / 0	ns
		XCV400E	2.0 / 0	2.0 / 0	2.0 / 0	2.0 / 0	ns
		XCV600E	2.1 / 0	2.1 / 0	2.1 / 0	2.1 / 0	ns
		XCV1000E	2.3 / 0	2.3 / 0	2.3 / 0	2.3 / 0	ns
		XCV1600E	2.5 / 0	2.5 / 0	2.5 / 0	2.5 / 0	ns
		XCV2000E	2.5 / 0	2.5 / 0	2.5 / 0	2.5 / 0	ns
		XCV2600E	2.7 / 0	2.7 / 0	2.7 / 0	2.7 / 0	ns
		XCV3200E	2.8 / 0	2.8 / 0	2.8 / 0	2.8 / 0	ns

Notes:

1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P137	VCCINT	NA
P104	VCCINT	NA
P88	VCCINT	NA
P77	VCCINT	NA
P43	VCCINT	NA
P32	VCCINT	NA
P16	VCCINT	NA
P240	VCCO	7
P232	VCCO	0
P226	VCCO	0
P212	VCCO	0
P207	VCCO	1
P197	VCCO	1
P180	VCCO	1
P176	VCCO	2
P165	VCCO	2
P150	VCCO	2
P146	VCCO	3
P136	VCCO	3
P121	VCCO	3
P116	VCCO	4
P105	VCCO	4
P90	VCCO	4
P85	VCCO	5
P76	VCCO	5
P61	VCCO	5
P55	VCCO	6
P44	VCCO	6
P30	VCCO	6
P25	VCCO	7
P15	VCCO	7
P233	GND	NA
P227	GND	NA

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P219	GND	NA
P211	GND	NA
P204	GND	NA
P196	GND	NA
P190	GND	NA
P182	GND	NA
P172	GND	NA
P166	GND	NA
P158	GND	NA
P151	GND	NA
P143	GND	NA
P135	GND	NA
P129	GND	NA
P119	GND	NA
P112	GND	NA
P106	GND	NA
P98	GND	NA
P91	GND	NA
P83	GND	NA
P75	GND	NA
P69	GND	NA
P59	GND	NA
P51	GND	NA
P45	GND	NA
P37	GND	NA
P29	GND	NA
P22	GND	NA
P14	GND	NA
P8	GND	NA
P1	GND	NA

Notes:

1. V_{REF} or I/O option only in the XCV100E, 200E, 300E, 400E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E, 400E; otherwise, I/O option only.
3. V_{REF} or I/O option only in the XCV400E; otherwise, I/O option only.

HQ240 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 9: HQ240 Differential Pin Pair Summary
XCV600E, XCV1000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	P92	P93	NA	IO_DLL_L40P
1	5	P89	P87	NA	IO_DLL_L40N
2	1	P210	P209	NA	IO_DLL_L6P
3	0	P213	P215	NA	IO_DLL_L6N
IO LVDS					
Total Pairs: 64, Asynchronous Output Pairs: 53					
0	0	P236	P237	NA	VREF
1	0	P234	P235	✓	-
2	0	P228	P229	✓	VREF
3	0	P223	P224	✓	-
4	0	P220	P221	✓	-
5	0	P217	P218	✓	VREF
6	1	P209	P215	NA	IO_LVDS_DLL
7	1	P205	P206	✓	VREF
8	1	P202	P203	✓	-
9	1	P199	P200	✓	-
10	1	P194	P195	✓	VREF
11	1	P191	P192	✓	VREF
12	1	P188	P189	✓	-
13	1	P186	P187	NA	VREF
14	1	P184	P185	✓	CS
15	2	P178	P177	✓	DIN, D0

Table 9: HQ240 Differential Pin Pair Summary
XCV600E, XCV1000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	2	P174	P173	✓	-
17	2	P171	P170	✓	VREF
18	2	P168	P167	✓	D1
19	2	P163	P162	✓	D2
20	2	P160	P159	✓	-
21	2	P157	P156	✓	D3
22	2	P155	P154	1	VREF
23	2	P153	P152	✓	-
24	3	P145	P144	✓	D4, VREF
25	3	P142	P141	✓	-
26	3	P139	P138	✓	D5
27	3	P134	P133	✓	VREF
28	3	P131	P130	✓	VREF
29	3	P128	P127	✓	-
30	3	P126	P125	1	VREF
31	3	P124	P123	✓	INIT
32	4	P118	P117	✓	-
33	4	P114	P113	✓	-
34	4	P111	P110	✓	VREF
35	4	P108	P107	✓	VREF
36	4	P103	P102	✓	-
37	4	P100	P99	✓	-
38	4	P97	P96	✓	VREF
39	4	P95	P94	NA	VREF
40	5	P93	P87	NA	IO_LVDS_DLL
41	5	P84	P82	NA	VREF
42	5	P79	P78	✓	-
43	5	P74	P73	✓	VREF
44	5	P71	P70	✓	VREF
45	5	P68	P67	✓	-
46	5	P66	P65	NA	VREF
47	5	P64	P63	✓	-

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
4	IO_L70N_Y	AK4
4	IO_L71P_YY	AJ5
4	IO_L71N_YY	AH6
4	IO_VREF_L72P_YY	AL4
4	IO_L72N_YY	AK5
4	IO_L73P_Y	AJ6
4	IO_L73N_Y	AH7
4	IO_L74P_YY	AL5
4	IO_L74N_YY	AK6
4	IO_VREF_L75P_YY	AJ7
4	IO_L75N_YY	AL6
4	IO_L76P_Y	AH9
4	IO_L76N_Y	AJ8
4	IO_VREF_L77P_Y	AK8 ¹
4	IO_L77N_Y	AJ9
4	IO_VREF_L78P_YY	AL8
4	IO_L78N_YY	AK9
4	IO_L79P_YY	AK10
4	IO_L79N_YY	AL10
4	IO_L80P_YY	AH12
4	IO_L80N_YY	AK11
4	IO_L81P_YY	AJ12
4	IO_L81N_YY	AK12
4	IO_L82P_YY	AH13
4	IO_L82N_YY	AJ13
4	IO_VREF_L83P_YY	AL13
4	IO_L83N_YY	AK14
4	IO_L84P_Y	AH14
4	IO_L84N_Y	AJ14
4	IO_VREF_L85P_Y	AK15 ²
4	IO_L85N_Y	AJ15
4	IO_LVDS_DLL_L86P	AH15
5	GCK1	AK16
5	IO	AH20
5	IO	AJ19

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
5	IO	AJ23
5	IO	AJ24
5	IO_LVDS_DLL_L86N	AL17
5	IO_L87P_Y	AK17
5	IO_VREF_L87N_Y	AJ17 ²
5	IO_L88P_Y	AH17
5	IO_L88N_Y	AK18
5	IO_L89P_YY	AL19
5	IO_VREF_L89N_YY	AJ18
5	IO_L90P_YY	AH18
5	IO_L90N_YY	AL20
5	IO_L91P_YY	AK20
5	IO_L91N_YY	AH19
5	IO_L92P_YY	AJ20
5	IO_L92N_YY	AK21
5	IO_L93P_YY	AJ21
5	IO_L93N_YY	AL22
5	IO_L94P_YY	AJ22
5	IO_VREF_L94N_YY	AK23
5	IO_L95P_Y	AH22
5	IO_VREF_L95N_Y	AL24 ¹
5	IO_L96P_Y	AK24
5	IO_L96N_Y	AH23
5	IO_L97P_YY	AK25
5	IO_VREF_L97N_YY	AJ25
5	IO_L98P_YY	AL26
5	IO_L98N_YY	AK26
5	IO_L99P_Y	AH25
5	IO_L99N_Y	AL27
5	IO_L100P_YY	AJ26
5	IO_VREF_L100N_YY	AK27
5	IO_L101P_YY	AH26
5	IO_L101N_YY	AL28
5	IO_L102P_Y	AJ27
5	IO_L102N_Y	AK28

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
7	IO_L74N_Y	G4
7	IO_VREF_L74P_Y	H3
7	IO_L75N_YY	G2
7	IO_L75P_YY	F5
7	IO_L76N	F4
7	IO_L76P	F1
7	IO_L77N_YY	G3
7	IO_L77P_YY	F2
7	IO_L78N_Y	E1
7	IO_VREF_L78P_Y	D1 ¹
7	IO_L79N	E4
7	IO_L79P	E2
7	IO_L80N_Y	F3
7	IO_VREF_L80P_Y	C1
7	IO_L81N_YY	D2
7	IO_L81P_YY	E3
7	IO_VREF_L82N	B1 ²
7	IO_L82P	A2
2	CCLK	D15
3	DONE	R14
NA	DXN	R4
NA	DXP	P4
NA	M0	N3
NA	M1	P2
NA	M2	R3
NA	PROGRAM	P15
NA	TCK	C4
NA	TDI	A15
2	TDO	B14
NA	TMS	D3
NA	VCCINT	C3
NA	VCCINT	C14
NA	VCCINT	D4

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
NA	VCCINT	D13
NA	VCCINT	E5
NA	VCCINT	E12
NA	VCCINT	M5
NA	VCCINT	M12
NA	VCCINT	N4
NA	VCCINT	N13
NA	VCCINT	P3
NA	VCCINT	P14
0	VCCO	F8
0	VCCO	E8
1	VCCO	F9
1	VCCO	E9
2	VCCO	H12
2	VCCO	H11
3	VCCO	J12
3	VCCO	J11
4	VCCO	M9
4	VCCO	L9
5	VCCO	M8
5	VCCO	L8
6	VCCO	J6
6	VCCO	J5
7	VCCO	H6
7	VCCO	H5
NA	GND	T16
NA	GND	T1
NA	GND	R15
NA	GND	R2
NA	GND	L11
NA	GND	L10
NA	GND	L7
NA	GND	L6

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	B8	A8	√	VREF
53	1	A7	D9	√	-
54	1	B7	C8	3	-
55	1	A6	D8	3	-
56	1	B6	C7	√	VREF
57	1	A5	D7	√	-
58	1	B5	C6	5	VREF
59	1	A4	D6	5	-
60	1	D5	B4	√	CS
61	2	E3	C2	√	DIN, D0
62	2	D3	F3	6	-
63	2	D2	G4	4	VREF
64	2	G3	E2	4	-
65	2	H4	E1	6	VREF
66	2	H3	F2	√	-
67	2	J4	F1	4	-
68	2	J3	G2	6	-
69	2	G1	K4	√	VREF
70	2	H2	K3	√	-
71	2	H1	L4	7	VREF
72	2	J2	L3	4	-
73	2	J1	M3	√	VREF
74	2	K2	N4	√	-
75	2	K1	N3	4	-
76	2	L2	P4	√	D1
77	2	P3	L1	√	D2
78	2	R4	M2	6	-
79	2	R3	M1	4	-
80	2	T4	N2	4	-
81	2	N1	T3	6	VREF
82	2	P2	U5	√	-
83	2	P1	U4	4	-
84	2	R2	U3	6	-
85	2	V5	R1	√	D3

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	2	V4	T2	√	-
87	2	V3	T1	7	-
88	2	W4	U2	4	-
89	2	W3	U1	√	VREF
90	2	AA3	V2	√	-
91	2	AA4	V1	4	VREF
92	2	AB2	W2	√	-
93	3	AB4	W1	4	VREF
94	3	AB5	Y2	√	-
95	3	AC2	Y1	√	VREF
96	3	AC3	AA1	4	-
97	3	AC4	AA2	7	-
98	3	AC5	AB1	√	-
99	3	AD3	AC1	√	VREF
100	3	AD1	AD4	6	-
101	3	AD2	AE3	4	-
102	3	AE1	AE4	√	-
103	3	AE2	AF3	6	VREF
104	3	AF4	AF1	4	-
105	3	AG3	AF2	4	-
106	3	AG4	AG1	6	-
107	3	AH3	AG2	√	D5
108	3	AH1	AJ2	√	VREF
109	3	AH2	AJ3	4	-
110	3	AJ1	AJ4	√	-
111	3	AK1	AK3	√	VREF
112	3	AK2	AK4	4	-
113	3	AL1	AL2	7	VREF
114	3	AM1	AL3	√	-
115	3	AM2	AL4	√	VREF
116	3	AM3	AN1	6	-
117	3	AM4	AP1	4	-
118	3	AN2	AP2	√	-
119	3	AN3	AR1	6	VREF

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	3	AN4	AT1	4	-
121	3	AR2	AP4	4	VREF
122	3	AT2	AR3	6	-
123	3	AR4	AU2	√	INIT
124	4	AU4	AV5	√	-
125	4	AT6	AV4	5	-
126	4	AU6	AW4	5	VREF
127	4	AT7	AW5	√	-
128	4	AU7	AV6	√	VREF
129	4	AT8	AW6	3	-
130	4	AU8	AV7	3	-
131	4	AT9	AW7	√	-
132	4	AV8	AU9	√	VREF
133	4	AW8	AT10	5	-
134	4	AV9	AU10	5	VREF
135	4	AW9	AT11	√	-
136	4	AV10	AU11	√	VREF
137	4	AW10	AU12	2	-
138	4	AV11	AT13	2	-
139	4	AW11	AU13	√	VREF
140	4	AT14	AV12	√	-
141	4	AU14	AW12	5	-
142	4	AT15	AV13	5	-
143	4	AU15	AW13	√	-
144	4	AV14	AT16	√	VREF
145	4	AW14	AU16	3	-
146	4	AV15	AR17	3	-
147	4	AW15	AT17	√	-
148	4	AU17	AV16	√	VREF
149	4	AR18	AW16	5	-
150	4	AT18	AV17	5	-
151	4	AU18	AW17	√	-
152	4	AT19	AV18	√	VREF
153	4	AU19	AW18	2	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	4	AU21	AV19	2	VREF
155	5	AT21	AT22	NA	IO_LVDS_DLL
156	5	AV20	AR22	8	VREF
157	5	AV23	AW21	√	VREF
158	5	AU23	AV21	√	-
159	5	AT23	AW22	5	-
160	5	AR23	AV22	5	-
161	5	AV24	AW23	√	VREF
162	5	AW24	AU24	√	-
163	5	AW25	AT24	3	-
164	5	AV25	AU25	3	-
165	5	AW26	AT25	√	VREF
166	5	AV26	AW27	√	-
167	5	AU26	AV27	5	-
168	5	AT26	AW28	5	-
169	5	AU27	AV28	√	-
170	5	AW29	AT27	√	VREF
171	5	AW30	AU28	2	-
172	5	AV30	AV29	2	-
173	5	AW31	AU29	√	VREF
174	5	AV31	AT29	√	-
175	5	AW32	AU30	5	VREF
176	5	AW33	AT30	5	-
177	5	AV33	AU31	√	VREF
178	5	AT31	AW34	√	-
179	5	AV32	AV34	3	-
180	5	AU32	AW35	3	-
181	5	AT32	AV35	√	VREF
182	5	AU33	AW36	√	-
183	5	AT33	AV36	5	VREF
184	5	AU34	AU36	5	-
185	6	AT38	AR36	√	-
186	6	AP36	AR38	6	-
187	6	AP37	AT39	4	VREF

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	IO_L6N_Y	A5
0	IO_L6P_Y	F8
0	IO_L7N_Y	D7
0	IO_L7P_Y	N11
0	IO_L8N_YY	G9
0	IO_L8P_YY	E8
0	IO_VREF_L9N_YY	A6
0	IO_L9P_YY	J11
0	IO_L10N_Y	C7
0	IO_L10P_Y	B7
0	IO_L11N_Y	C8
0	IO_L11P_Y	H10
0	IO_L12N_YY	G10
0	IO_L12P_YY	F10
0	IO_VREF_L13N_YY	A8
0	IO_L13P_YY	H11
0	IO_L14N	D9 ⁴
0	IO_L14P	C9 ³
0	IO_L15N_YY	B9
0	IO_L15P_YY	J12
0	IO_L16N	E10 ⁴
0	IO_VREF_L16P	A9
0	IO_L17N	G11
0	IO_L17P	B10
0	IO_L18N_YY	H12 ⁴
0	IO_L18P_YY	C10 ⁴
0	IO_L19N_Y	H13
0	IO_L19P_Y	F11
0	IO_L20N_Y	E11
0	IO_L20P_Y	D11
0	IO_L21N_Y	B11 ⁴
0	IO_L21P_Y	G12 ⁴
0	IO_L22N_YY	F12
0	IO_L22P_YY	C11
0	IO_VREF_L23N_YY	A10 ¹
0	IO_L23P_YY	D12
0	IO_L24N_Y	E12

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	IO_L24P_Y	A11
0	IO_L25N_Y	G13
0	IO_L25P_Y	B12
0	IO_L26N_YY	A12
0	IO_L26P_YY	K13
0	IO_VREF_L27N_YY	F13
0	IO_L27P_YY	B13
0	IO_L28N_Y	G14
0	IO_L28P_Y	E13
0	IO_L29N_Y	D14
0	IO_L29P_Y	B14
0	IO_L30N_YY	A14
0	IO_L30P_YY	J14
0	IO_VREF_L31N_YY	K14
0	IO_L31P_YY	J15
0	IO_L32N	B15 ⁴
0	IO_L32P	H15 ³
0	IO_VREF_L33N_YY	F15 ^{2,3}
0	IO_L33P_YY	D15 ⁴
0	IO_LVDS_DLL_L34N	A15
1	GCK2	E15
1	IO	A25 ⁴
1	IO	B17 ⁴
1	IO	B18 ⁴
1	IO	C23 ⁴
1	IO	D16 ⁴
1	IO	D17 ⁵
1	IO	D23 ⁴
1	IO	E19 ⁴
1	IO	E24 ⁵
1	IO	F22 ⁴
1	IO	G17 ⁵
1	IO	G20 ⁴
1	IO	J16 ⁴
1	IO	J17 ⁴
1	IO	J19 ⁵

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
1	IO	J20 ⁵
1	IO	L18 ⁴
1	IO_LVDS_DLL_L34P	E16
1	IO_L35N_YY	B16
1	IO_VREF_L35P_YY	F16 ²
1	IO_L36N_YY	A16
1	IO_L36P_YY	H16
1	IO_L37N_YY	C16
1	IO_VREF_L37P_YY	K15
1	IO_L38N_YY	K16
1	IO_L38P_YY	G16
1	IO_L39N_Y	A17
1	IO_L39P_Y	E17
1	IO_L40N_Y	F17
1	IO_L40P_Y	C17
1	IO_L41N_YY	E18
1	IO_VREF_L41P_YY	A18
1	IO_L42N_YY	D18
1	IO_L42P_YY	A19
1	IO_L43N_Y	B19
1	IO_L43P_Y	G18
1	IO_L44N_Y	D19
1	IO_L44P_Y	H18
1	IO_L45N_YY	F18
1	IO_VREF_L45P_YY	F19 ¹
1	IO_L46N_YY	B20
1	IO_L46P_YY	K17
1	IO_L47N_Y	D20 ⁴
1	IO_L47P_Y	A20 ⁴
1	IO_L48N_Y	G19
1	IO_L48P_Y	C20
1	IO_L49N_Y	K18
1	IO_L49P_Y	E20
1	IO_L50N_YY	B21 ⁴
1	IO_L50P_YY	D21 ⁴
1	IO_L51N_YY	F20
1	IO_L51P_YY	A21

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
1	IO_L52N_YY	C21
1	IO_VREF_L52P_YY	A22
1	IO_L53N_YY	H19
1	IO_L53P_YY	B22
1	IO_L54N_YY	E21
1	IO_L54P_YY	D22
1	IO_L55N_YY	F21
1	IO_VREF_L55P_YY	C22
1	IO_L56N_YY	H20
1	IO_L56P_YY	E22
1	IO_L57N_Y	G21
1	IO_L57P_Y	A23
1	IO_L58N_Y	A24
1	IO_L58P_Y	K19
1	IO_L59N_YY	C24
1	IO_VREF_L59P_YY	B24
1	IO_L60N_YY	H21
1	IO_L60P_YY	G22
1	IO_L61N_Y	E23
1	IO_L61P_Y	C25
1	IO_L62N_Y	D24
1	IO_L62P_Y	A26
1	IO_L63N_YY	B26
1	IO_VREF_L63P_YY	K20
1	IO_L64N_YY	D25
1	IO_L64P_YY	J21
1	IO_L65N_Y	C26 ⁴
1	IO_L65P_Y	F23 ⁴
1	IO_L66N_Y	B27
1	IO_VREF_L66P_Y	G23 ¹
1	IO_L67N_Y	A27
1	IO_L67P_Y	F24
1	IO_L68N_YY	B28 ³
1	IO_L68P_YY	A28 ⁴
1	IO_WRITE_L69N_YY	K21
1	IO_CS_L69P_YY	C27

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
2	IO_L99P_YY	N26
2	IO_L99N_YY	P28
2	IO_L100P	P29
2	IO_L100N	N24
2	IO_L101P_YY	P22
2	IO_L101N_YY	R26
2	IO_VREF_L102P_YY	P25
2	IO_L102N_YY	R29
2	IO_L103P_YY	R21 ⁴
2	IO_L103N_YY	R28 ³
2	IO_VREF_L104P_YY	R25 ²
2	IO_L104N_YY	T30
2	IO_L105P_YY	P24 ⁴
2	IO_L105N_YY	R27 ³
2	IO_L106P	R24
3	IO	T22 ⁴
3	IO	T24 ⁴
3	IO	T26 ⁴
3	IO	T29 ⁴
3	IO	U26 ⁵
3	IO	V23 ⁴
3	IO	V25 ⁴
3	IO	V30 ⁵
3	IO	Y21 ⁴
3	IO	AA26 ⁴
3	IO	AA23 ⁴
3	IO	AB27 ⁴
3	IO	AB29 ⁴
3	IO	AC28 ⁵
3	IO	AD26 ⁴
3	IO	AD29 ⁵
3	IO	AE27 ⁵
3	IO_L106N	U29
3	IO_L107P_YY	R22
3	IO_VREF_L107N_YY	T27 ²
3	IO_L108P_YY	R23

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
3	IO_L108N_YY	T28
3	IO_L109P_YY	T21
3	IO_VREF_L109N_YY	T25
3	IO_L110P_YY	U28
3	IO_L110N_YY	U30
3	IO_L111P	T23
3	IO_L111N	U27
3	IO_L112P_YY	U25
3	IO_L112N_YY	V27
3	IO_D4_L113P_YY	U24
3	IO_VREF_L113N_YY	V29
3	IO_L114P	W30
3	IO_L114N	U22
3	IO_L115P_YY	U21
3	IO_L115N_YY	W29
3	IO_L116P_YY	V26
3	IO_L116N_YY	W27
3	IO_L117P	W26
3	IO_VREF_L117N	Y29 ¹
3	IO_L118P_YY	W25
3	IO_L118N_YY	Y30
3	IO_L119P_Y	V24 ⁴
3	IO_L119N_Y	Y28 ⁴
3	IO_L120P_YY	AA30
3	IO_L120N_YY	W24
3	IO_L121P	AA29
3	IO_L121N	V20
3	IO_L122P	Y27 ⁴
3	IO_L122N	W23 ⁴
3	IO_L123P_YY	Y26
3	IO_D5_L123N_YY	AB30
3	IO_D6_L124P_YY	V21
3	IO_VREF_L124N_YY	AA28
3	IO_L125P_YY	Y25
3	IO_L125N_YY	AA27
3	IO_L126P_YY	W22
3	IO_L126N_YY	Y23

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
0	IO_L6P_YY	H10 ⁵
0	IO_L7N_Y	D7
0	IO_L7P_Y	B5
0	IO_L8N_Y	K12
0	IO_L8P_Y	E8
0	IO_L9N	B6 ⁴
0	IO_L9P	F9 ⁵
0	IO_L10N_YY	G10
0	IO_L10P_YY	C7
0	IO_VREF_L11N_YY	D8
0	IO_L11P_YY	B7
0	IO_L12N	H11 ⁴
0	IO_L12P	C8 ⁵
0	IO_L13N_Y	E9
0	IO_L13P_Y	B8
0	IO_VREF_L14N_Y	K13 ²
0	IO_L14P_Y	G11
0	IO_L15N	A8 ⁴
0	IO_L15P	F10 ⁵
0	IO_L16N_YY	C9
0	IO_L16P_YY	H12
0	IO_VREF_L17N_YY	D10
0	IO_L17P_YY	A9
0	IO_L18N_Y	F11
0	IO_L18P_Y	A10
0	IO_L19N_Y	K14
0	IO_L19P_Y	C10
0	IO_VREF_L20N_YY	H13
0	IO_L20P_YY	G12
0	IO_L21N_YY	A11
0	IO_L21P_YY	B11
0	IO_L22N_Y	E12
0	IO_L22P_Y	D11
0	IO_L23N_Y	G13

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
0	IO_L23P_Y	C12
0	IO_L24N_Y	K15
0	IO_L24P_Y	A12
0	IO_L25N_Y	B12
0	IO_L25P_Y	H14
0	IO_L26N_YY	D12
0	IO_L26P_YY	F13
0	IO_VREF_L27N_YY	A13
0	IO_L27P_YY	B13
0	IO_L28N_YY	J15 ⁴
0	IO_L28P_YY	G14 ⁵
0	IO_L29N_Y	C13
0	IO_L29P_Y	F14
0	IO_L30N_Y	H15
0	IO_L30P_Y	D13
0	IO_L31N	A14 ⁴
0	IO_L31P	K16 ⁵
0	IO_L32N_YY	E14
0	IO_L32P_YY	B14
0	IO_VREF_L33N_YY	G15
0	IO_L33P_YY	D14
0	IO_L34N	J16 ⁴
0	IO_L34P	D15 ⁵
0	IO_L35N_Y	F15
0	IO_L35P_Y	B15
0	IO_L36N_Y	A15
0	IO_L36P_Y	E15
0	IO_L37N	G16 ⁴
0	IO_L37P	A16 ⁵
0	IO_L38N_YY	F16
0	IO_L38P_YY	J17
0	IO_VREF_L39N_YY	C16
0	IO_L39P_YY	B16
0	IO_L40N_Y	H17

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCO_7	K5
NA	VCCO_7	F1
NA	VCCO_7	T11
NA	VCCO_7	T12
NA	VCCO_7	R11
NA	VCCO_7	R12
NA	VCCO_7	P3
NA	VCCO_7	P11
NA	VCCO_7	P12
NA	VCCO_7	N11
NA	GND	K32
NA	GND	R4
NA	GND	AN1
NA	GND	AM11
NA	GND	AK5
NA	GND	AH28
NA	GND	AD32
NA	GND	AA20
NA	GND	Y20
NA	GND	W19
NA	GND	V19
NA	GND	U20
NA	GND	T20
NA	GND	R19
NA	GND	P19
NA	GND	H8
NA	GND	F12
NA	GND	C2
NA	GND	B1
NA	GND	A7
NA	GND	AP1
NA	GND	AN2
NA	GND	AM15

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	GND	AK17
NA	GND	AH34
NA	GND	AC6
NA	GND	AA21
NA	GND	Y21
NA	GND	W20
NA	GND	V20
NA	GND	U21
NA	GND	T21
NA	GND	R20
NA	GND	P20
NA	GND	H16
NA	GND	F23
NA	GND	C3
NA	GND	B2
NA	GND	A28
NA	GND	AP34
NA	GND	AM3
NA	GND	AL31
NA	GND	AH7
NA	GND	AD3
NA	GND	AA19
NA	GND	Y19
NA	GND	W18
NA	GND	V18
NA	GND	U19
NA	GND	T19
NA	GND	R18
NA	GND	P18
NA	GND	J26
NA	GND	F6
NA	GND	C1
NA	GND	C34
NA	GND	A3

Date	Version	Revision
4/2/01	2.0	- Updated numerous values in Virtex-E Switching Characteristics tables. - Changed pinout table footnotes from "V_{REF} option only" to "V_{REF} or I/O option only" to improve clarity. - Converted file to modularized format. See the Virtex-E Data Sheet section.
7/26/01	2.1	- Changed pinout table footnotes from "V_{REF} or I/O option only" to "V_{REF} or I/O option only; otherwise I/O only" to improve clarity. - Changed designation for pin pair 300 in Table 29 from AO to footnote 9.
10/25/01	2.2	- Changed Table 29 to clarify which devices in the FG1156 package can use each pin pair as an asynchronous output. - Updated references to the XCV3200E device in the FG1156 package.
11/15/01	2.3	Fixed cosmetic error.
07/17/02	2.4	- Added "VREF" to the description for pin B15 in Table 12. - Changed designation for pin pair 129 in Table 15 from AO to "AO in the XCV1000E, 1600E, 2000E". - Data sheet designation upgraded from Preliminary to Production.
03/14/03	2.5	Removed the Virtex-E XCV300E section under Pinout Differences Between Virtex and Virtex-E Families (and revised Table 1), since these differences do not exist.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
[Introduction and Ordering Information \(Module 1\)](#)
- DS022-2, Virtex-E 1.8V FPGAs:
[Functional Description \(Module 2\)](#)
- DS022-3, Virtex-E 1.8V FPGAs:
[DC and Switching Characteristics \(Module 3\)](#)
- DS022-4, Virtex-E 1.8V FPGAs:
[Pinout Tables \(Module 4\)](#)